

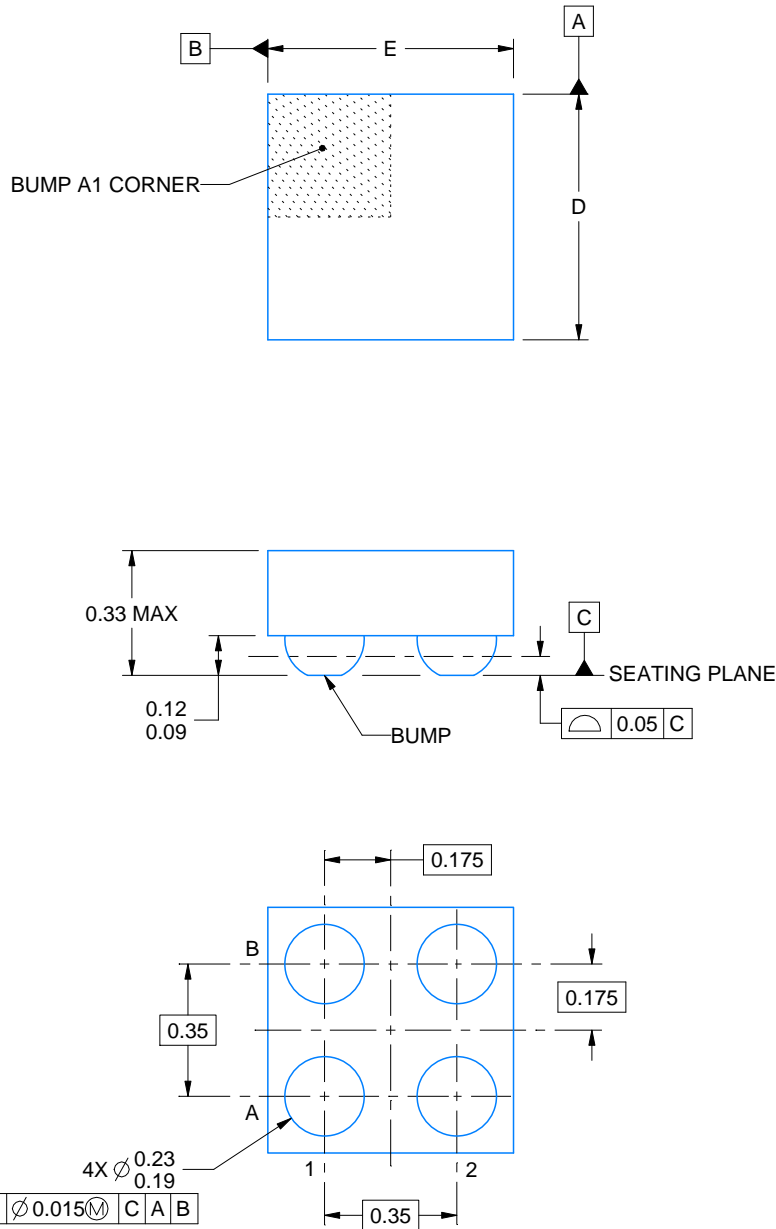
YKG0004



# PACKAGE OUTLINE

DSBGA - 0.33mm MAX HEIGHT

DIE SIZE BALL GRID ARRAY



4218366/D 11/2017

NOTES:

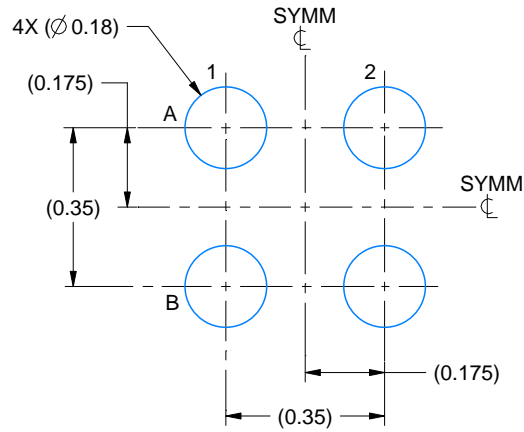
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

# EXAMPLE BOARD LAYOUT

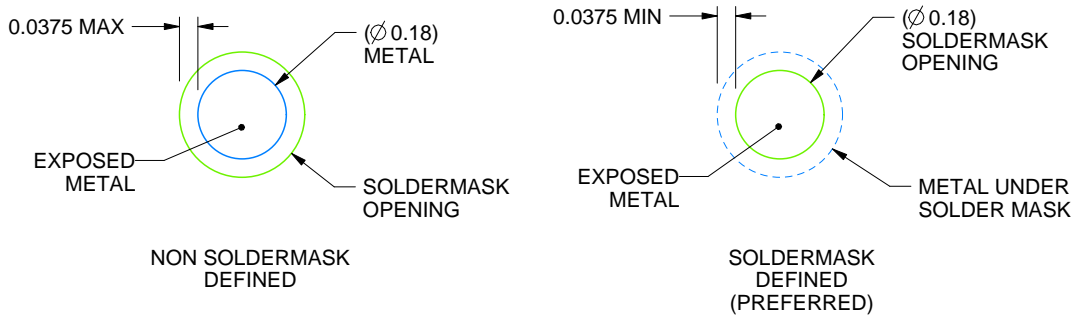
YKG0004

DSBGA - 0.33mm MAX HEIGHT

DIE SIZE BALL GRID ARRAY



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:60X



SOLDERMASK DETAILS  
NOT TO SCALE

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NOTES: (continued)

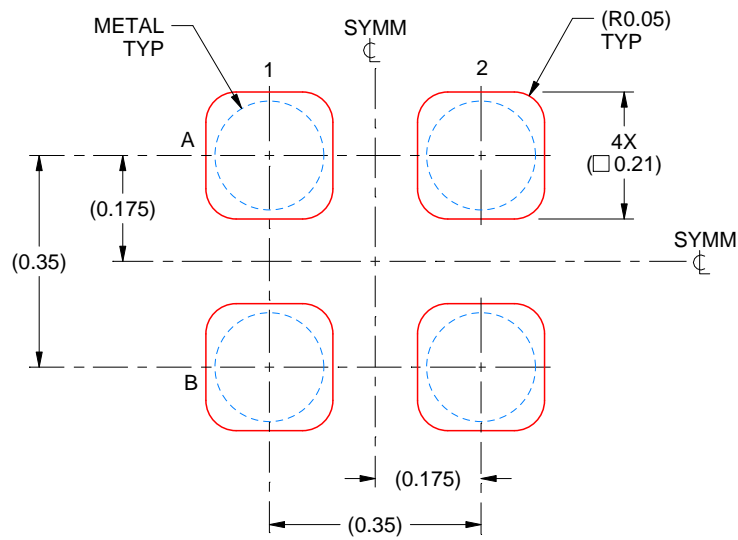
- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. Refer to Texas Instruments Literature No. SNVA009 ([www.ti.com/lit/snva009](http://www.ti.com/lit/snva009)).

# EXAMPLE STENCIL DESIGN

YKG0004

DSBGA - 0.33mm MAX HEIGHT

DIE SIZE BALL GRID ARRAY



SOLDERPASTE EXAMPLE  
BASED ON 0.075 mm THICK STENCIL  
SCALE:80X

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NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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